

**HDAF SERIES**

(2.00 mm) .0787"

# RUGGED ELEVATED HIGH-DENSITY ARRAY

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?HDAF](http://www.samtec.com?HDAF)

**Insulator Material:**

Black LCP

**Contact Material:**

Copper Alloy

**Plating:**

Au or Sn over

50 μ" (1.27 μm) Ni

**Current Rating:**

3.4 A per pin

(6 adjacent pins powered)

**Operating Temp Range:**

-55 °C to +125 °C

**Working Voltage:**

200 VAC

**Mated Cycles:**

100

**RoHS Compliant:**

Yes

**Lead-Free Solderable:**

Yes

Mates with:

HDAM

Intermateable with Molex HD Mezz

Open-pin-field for Single-Ended or Differential Pair configurations

299, 195 and 143 pins

Lead-Free Solder Charge

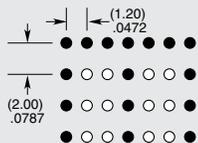
Elevated stack heights of 20 mm, 25 mm, 30 mm and 35 mm

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



## DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

\*2:1 S:G Ratio

## ALSO AVAILABLE (MOQ Required)

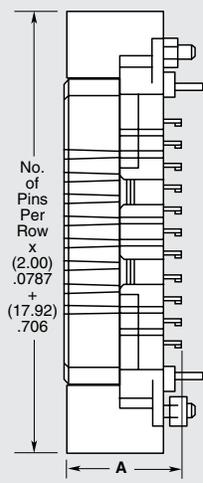
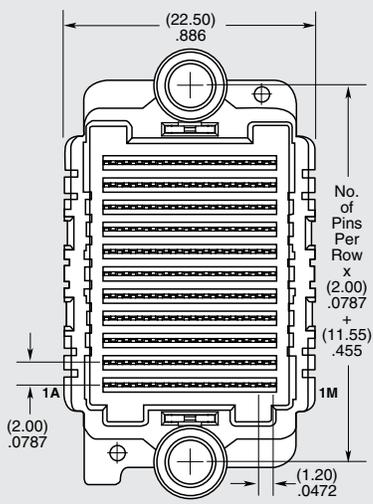
- Tin-Lead Solder Charge
- Other platings

**Notes:**

HD Mezz is a trademark of Molex Incorporated

Some lengths, styles and options are non-standard, non-returnable.

HDAF	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	13	SOLDER TYPE	OPTION	PACKAGING
	-11, -15, -23	Specify LEAD STYLE from chart	-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on tails and guide pins		-2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/0.7% Cu Solder Charge	-P = Pick & Place Pad	Leave blank for tray packaging -TR = Tape & Reel -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)



LEAD STYLE	A
-08.0	(10.51) .414
-18.0	(20.51) .807